CHANNEL TALK

Laird
A DuPont Business

AUGUST 2025

LAIRD TO BECOME A PART OF QNITY

Qnity™

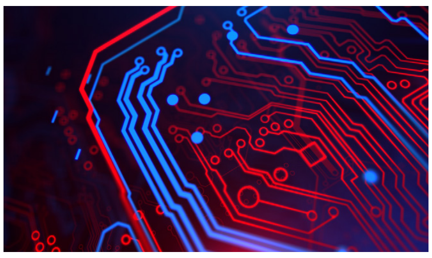
On November 1st, DuPont is set to spin off Laird Technologies and its other electronics industry businesses and form Qnity Electronics, an independent electronics company. As part of the transition, we will be migrating our social media presence to the Qnity LinkedIn page. **Please follow us here.** The DuPont Interconnect Solutions (ICS) LinkedIn page is being decommissioned later this year. Follow Qnity. It will become your quick and ideal way to stay updated on news and insights from Laird/ICS.

Qnity is to grow as a pure-play electronics materials firm and focus on becoming one of the largest, broadest solutions providers to the semiconductor and electronics industries. Laird's full product portfolio and those of other planned Qnity businesses will enable advanced computing, smart technologies, and connectivity. The DuPont spin-off gives Qnity added flexibility to respond to fast-changing electronics markets with greater agility and speed with the support of more than 10,000 employees in 80 countries. No changes for Laird channel partners are expected.

CREATE SPEEDY, LOW-VOLATILE SHIELDING

New from Laird is SNN1055HSLV, a form-in-place grade silicone paste delivering extremely low-volatile EMI shielding. Ultra-small bead paste dimensions are possible during high-speed automated dispensing. SNN1055HSLV is silver/nickel filled, and two-hours heat curable, delivering tight-fitting, cavity-to-cavity EMI shielding effectiveness across the 300 MHz to 40 GHz range. Besides its low volatility (CVCM<0.1%), and low outgassing, the enclosure material's overall balanced mechanical properties provide other additional benefits to data center, aerospace, automotive, and consumer electronics applications such as cellular phones and PCs. Get samples here.

BONDLINE: THINNER THAN A HUMAN HAIR

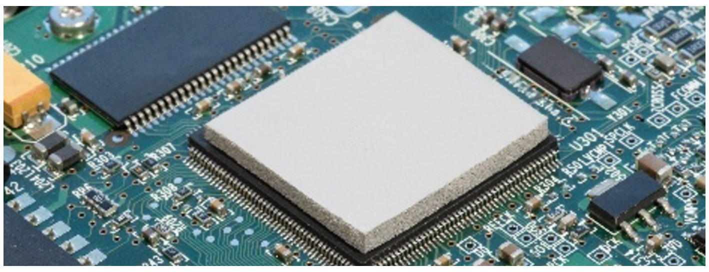


You can help prospects learn what's possible. See our new case study on an intricate heat transfer success which helped enable a major wearable technology manufacturer meet product launch deadlines. Facing "near-zero" PCB design space, our North American field application engineers succeeded by recommending Laird™ Tgel™ 600 thermal gel. Along with the customer's production line assembly team, they achieved precise, rapid gel dispensing and a microscopically thin bondline while creating a vital 18% thermal interface weight reduction from a previous product, thus satisfying device weight objectives. The 20-micron width bondline being applied during production by the manufacturer is narrower than a human hair, which averages 75 microns width. Analyze Tgel™ 600 samples soon.

SIGNALING SUCCESS IN ADVANCED DESIGNS

Channel partners can learn much more about our full inductive component line using our online booklet. No matter whether a customer's EMI/EMC problem is common or unique, Laird™ Steward™ solutions prove ideal, blending high performance within extremely compact, low-profile, space-saving designs. Our inductive component segment leadership extends across signal integrity and power magnetic products through a broad range of standardized and customized products. The line includes ferrite toroid and balun cores, cable cores, chip beads, SMT bead assemblies, common mode chokes, SMT power inductors, and wireless charging coil assemblies. Laird™ Steward™ also designs and manufactures many custom, high-performance products now supporting high DC current ratings with low DCR and minimal performance degradation under bias. A common small footprint makes our products suitable for power supply and DC/DC conversion designs in a variety of computing and other devices. See our 20-page Laird™ Steward™ product family booklet and learn more here.

ACHIEVE DESIRED GAP PAD REBOUND



A new and in-depth Laird white paper examines uneven or insufficient pad coverage of the thermal gap between a hot component and its heat sink following machine compression. The Laird-authored paper, based on a study, shows why poor rebound or spring back of the pad after it has been compressed onto a heat source can cause reduced pad performance or full thermal transfer failure. This and other thermo-mechanical stresses and vibration during assembly can cause actual thermal resistance to increase more than published ratings. The paper also examines the performance of the new, high deflection Laird™ Tflex™ HR 6.5 gap filler following machine application compression. Thorough lab analysis has confirmed that this advanced thermal transfer material quickly recovers and retains its low thermal resistance performance characteristics following machine compression. Order samples for testing today.

ELECTRONIC MATERIALS: THE BACKBONE OF AI

Read here how production issues facing integrated circuit substrate fabricators and the long-term and sufficient cooling of ICs are among key threats to AI's future. New investments in PCB processing materials are needed to produce dense, fine-line substrate circuitry. Beyond PCB fabrication, AI chip heat is soaring. AI chip wattage levels are expected to soon quadruple, yet how can designers and device manufacturers efficiently and effectively remove the rising heat? Read our co-authored, expert paper and learn why advanced electronic material innovations are hurdling big board-level obstacles confronting AI.

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